Buck/Boost High-Speed CAN/Dual LIN System Basis Chip Family

UJA113xHW

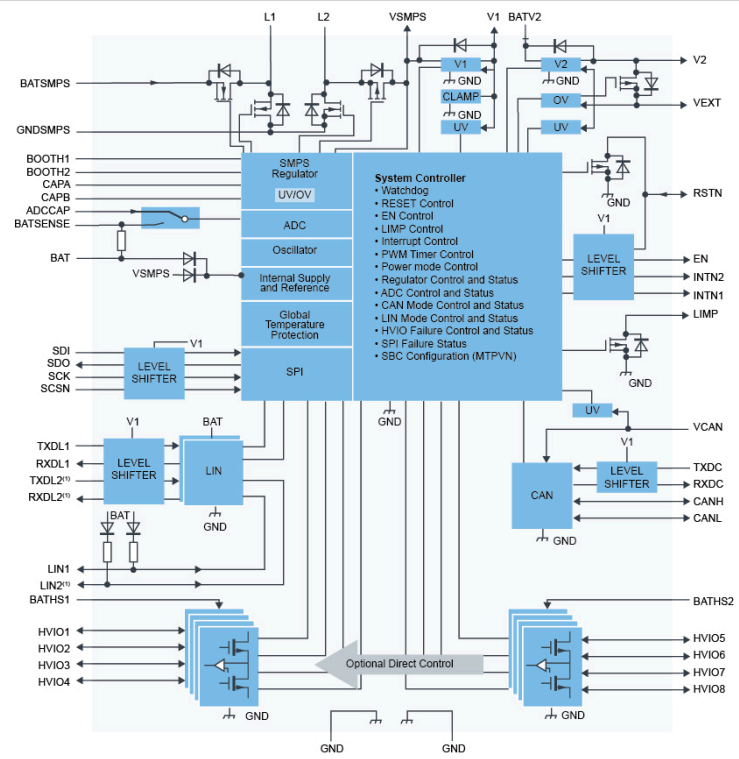
Last Updated: Jun 17, 2025

The UJA113x System Basis Chip (SBC) contains a fully integrated automatic SMPS Buck-Boost converter, a High-Speed CAN transceiver and up to two LIN transceivers along with a number of features commonly found in the latest generation of automotive Electronic Control Units (ECUs). It interfaces directly with CAN and LIN bus lines, supplies the microcontroller handles input and output signals and supports fail-safe features including a watchdog and advanced ‘limp home’ functionality configurable via non-volatile memory.

The UJA113x implements the High-Speed CAN physical layer as defined in the ISO 11898 standard (-2:2003, -5:2007, -6:2013) with additional timing parameters included, defining loop delay symmetry for CAN FD communication up to 2 Mbit/s.

UJA113xHW Block Diagram Block Diagram

UJA113x



View additional information for Buck/Boost High-Speed CAN/Dual LIN System Basis Chip Family.

Note: The information on this document is subject to change without notice.